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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/604,850	08/21/2003	Ping MEI	115252	1849
27074 75	90 06/07/2004		EXAMINER	
OLIFF & BERRIDGE, PLC.			ANYA, IGWE U	
P.O. BOX 19928 ALEXANDRIA, VA 22320			ART UNIT	PAPER NUMBER
ALEXANDIGA	VIL 22320		2825	
			DATE MAILED: 06/07/200	4

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)				
Office Action Summary		10/604,850	MEI ET AL.				
		Examiner	Art Unit				
		Igwe U. Anya	2825				
Period fo	The MAILING DATE of this communication r Reply	appears on the cover sheet w	ith the correspondence ac	idress			
THE I - Exter after - If the - If NO - Failu Any r	ORTENED STATUTORY PERIOD FOR REMAILING DATE OF THIS COMMUNICATION IN SIZE OF THIS COMMUNICATION	ON. FR 1.136(a). In no event, however, may a n. a reply within the statutory minimum of thi eriod will apply and will expire SIX (6) MOI statute, cause the application to become A	reply be timely filed rty (30) days will be considered timel NTHS from the mailing date of this c BANDONED (35 U.S.C. § 133).				
Status							
1)⊠	Responsive to communication(s) filed on 2	21 August 2003.					
2a) <u></u> □	This action is FINAL . 2b)⊠	This action is non-final.					
3)□	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Dispositi	on of Claims						
4)⊠ 5)□ 6)⊠ 7)⊠	4) Claim(s) 1-41 is/are pending in the application. 4a) Of the above claim(s) is/are withdrawn from consideration. 5) Claim(s) is/are allowed. 6) Claim(s) 1-24,32-37,39 and 40 is/are rejected. 7) Claim(s) 25-31,39 and 41 is/are objected to. 8) Claim(s) are subject to restriction and/or election requirement.						
Applicati	on Papers						
10)⊠	The specification is objected to by the Exarthe drawing(s) filed on <u>21 August 2003</u> is/of Applicant may not request that any objection to Replacement drawing sheet(s) including the control of the oath or declaration is objected to by the	are: a)⊠ accepted or b)⊡ of the drawing(s) be held in abeya prection is required if the drawing	nce. See 37 CFR 1.85(a). g(s) is objected to. See 37 C	FR 1.121(d).			
Priority u	nder 35 U.S.C. § 119						
a)[Acknowledgment is made of a claim for form All b) Some * c) None of: 1. Certified copies of the priority docum 2. Certified copies of the priority docum 3. Copies of the certified copies of the application from the International Butter the attached detailed Office action for a	nents have been received. nents have been received in A priority documents have beer ireau (PCT Rule 17.2(a)).	Application No n received in this National	Stage			
Attachmen	(s)						
1) Notice of References Cited (PTO-892) 4) Interview Summary (PTO-413)							
2) Notice Notice (3) Inform	e of Draftsperson's Patent Drawing Review (PTO-948 nation Disclosure Statement(s) (PTO-1449 or PTO/SE r No(s)/Mail Date 04062004.) Paper No	(s)/Mail Date Informal Patent Application (PTC	O-152)			

DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claims 1, 2, 9 14, and 21 24 are rejected under 35 U.S.C. 102(b) as being anticipated by Chua et al. (US Patent 6396677).
- 3. Chua teach a microelectromechanical system (MEMS), based sensor (col. 15 lines 37 65) comprising:

a substrate defining a plane (14), a first conductive material layer (15) having a first stress, a first portion (12) of the first conductive material layer being connected to the substrate and extending in a substantially parallel direction to the plane defined by the substrate (fig. 6), a second portion (11) of the first conductive material layer being disconnected from the substrate and extending in a substantially non parallel direction to the plane defined by the substrate; and

a semi conductive material layer formed over at least the second portion of the first conductive material layer (col. 9 lines 61 - 67), the semi conductive material layer having a second stress that is, less than the first stress of the first conductive material layer, wherein the first and second stresses form a stress gradient that bends the second portion of the first conductive material layer and the sensor material layer formed over the second portion of the first conductive material layer away from the

substrate, and further comprising a second conductive material layer formed over the semiconductor material layer, wherein at least a partial sub-layer of the semiconductor

material layer that is remote from the first conductive material layer has a reduced

stress that is less than the second stress. (col. 10 lines 20 - 46);

the second conductive material layer having a third stress that is less than the second stress of the semiconductor material layer; the first, second and third stresses forming a stress gradient that bends the second portion of the first conductive material layer, the sensor material layer formed over the second portion of the first conductive material layer and at least a portion of the second conductive material layer away from the substrate, wherein the first and second stresses are compressive stresses and the third stress is a tensile stress, thus forming a spring contact (col. 12 lines 1 – 42);

the conductive material comprising molybdenum-chromium (col. 16 lines 29 – 36); and

a back plate having a planar surface on which first and second semiconductor chips are mounted, and the chips communicate through the spring contact and wherein the back plate comprises a printed circuit board (col. 15 lines 33 – 43).

Claim Rejections - 35 USC § 103

4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the

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invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

- 5. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).
- 6. Claims 3 5, and 15 17 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chua et al. (US Patent 6396677) in view of Street et al. (US Patent 6429417).
- 7. Chua et al. teach the features previously outlined, but lack the spring contact semiconductor composed of material selected from a group consisting of polysilicon, amorphous silicon, and hydrogenated amorphous silicon that can be used being as sensing member in a probe card.
- 8. However, Street et al. teach a sensor material selected a group consisting polysilicon, amorphous silicon, and hydrogenated amorphous silicon (col. 4 line 61 col. 5 line 9).
- 9. Therefore, it would have been obvious to one of ordinary skill in the art to incorporate the teachings of Street et al. into the Chua et al. reference to form a highly transmissive sensor.

10. Claims 6, 7, 18, and 19 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chua et al. (US Patent 6396677) in view of Grudkowski et al. (US Patent 6300706).

- 11. The Chua reference teaches the features previously outlined, but lacks the sensor comprising Group III –V semiconductor material and gallium arsenide.
- 12. However, Grudkowski et al. teach a sensor comprising Group III –V semiconductor material and gallium arsenide (col. 2 lines 25 39).
- 13. Therefore, it would have been obvious to one of ordinary skill in the art to incorporate the teachings of Grudkowski et al. into the Chua et al. reference to form a piezoelectric sensor with enhanced sensitivity.
- 14. Claims 8, and 20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chua et al. (US Patent 6396677) in view of Biegelsen (US Patent 6267605).
- 15. The Chua reference teaches the features previously outlined, but lacks the conductive material comprising of titanium- tungsten material.
- 16. However, Biegelsen teach a conductive spring material comprising of a tungstenbased alloy for elasticity (col. 4 line 61 – col. 5 line 9).
- 17. Therefore, it would have been obvious to one of ordinary skill in the art to incorporate the teachings of Biegelsen into the Chua reference to form an elastic conductor.
- 18. Claims 32 37, 39 and 40 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chua et al. (US Patent 6396677) in view of Miracky et al. (US Patent 6636653).

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19. The Chua reference teaches the features previously outlined, but lacks a chip to chip communication comprising emitting optical signals by optical scanner or laser array from the first chip and receiving the signals using an array of MEMS signals on the second chip, a collimation lens array associated with the laser array of the first semiconductor chip, in-line calibration for optical link, and the laser array selected from

a group comprising an edge emitting laser array and a VCSEL laser array.

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- 20. However, Miracky et al. teach a chip to chip communication comprising emitting optical signals by optical scanner or laser array from the first chip and receiving the signals using an array of MEMS signals on the second chip (figs. 14 15B), a collimation lens array associated with the laser array of the first semiconductor chip (725), in-line calibration for optical link (col. 10 lines 48- 54), and the laser array selected from a group comprising an edge emitting laser array and a VCSEL laser array (col. 19 line 57 col. 20 line 12).
- 21. Therefore, it would have been obvious to one of ordinary skill in the art to incorporate the teachings of Miracky et al. into the Chua reference to form a monolithic integrated Optical MEMS.
- 22. Claims 25 31, 38, and 41 are objected to as being dependent upon a rejected claim, but would be allowable if rewritten in independent form.
- 23. Prior art considered, but not used in the rejection include Lemmi et al (USPAB 20030057533).

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24. Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Igwe U. Anya whose telephone number is (571) 272-

1887. The examiner can normally be reached on M - F 8:30am - 5:00pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Matthew S. Smith can be reached on (571) 272-1907. The fax phone

number for the organization where this application or proceeding is assigned is 703-

872-9306.

Information regarding the status of an application may be obtained from the

Patent Application Information Retrieval (PAIR) system. Status information for

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you have questions on access to the Private PAIR system, contact the Electronic

Business Center (EBC) at 866-217-9197 (toll-free).

Igwe U. Anya Examiner

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IA

May 19, 2004

MATTHEW SMITH SUPERVISORY PATENT EXAMINER

TECHNOLOGY CENTER 2800